

Title (en)  
METAL/CERAMIC SUBSTRATE

Title (de)  
METALL-KERAMIK-SUBSTRAT

Title (fr)  
SUBSTRAT MÉTAL-CÉRAMIQUE

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Application  
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Abstract (en)  
[origin: WO2010112000A1] The invention relates to a metal/ceramic substrate, comprising a multilayer, plate-shaped ceramic material and at least one metallization which is provided on a surface side of the ceramic material and joined to the ceramic material by direct bonding (DCB method) or reactive brazing, wherein the ceramic material comprises at least one inner layer or base layer made of a silicon nitride ceramic, and wherein the surface side of the ceramic material provided with the at least one metallization is formed on an intermediate layer which is applied onto the at least one base layer and made of an oxidic ceramic.

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